



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.037	0.043	0.94	1.10
A1	0.000	0.006	0.00	0.15
A2	0.030	0.037	0.75	0.95
D1	0.116	0.120	2.95	3.05
D2	0.114	0.118	2.89	3.00
E1	0.116	0.120	2.95	3.05
E2	0.114	0.118	2.89	3.00
E	0.187	0.199	4.75	5.05
L	0.0157	0.0275	0.40	0.70
L1	0.037	REF	0.940	REF
b	0.007	0.0106	0.177	0.270
e	0.0197	BSC	.500	BSC
c	0.0035	0.0078	0.090	0.200
S	0.0196	REF	.498	REF
α	0°	6°	0°	6°
*X	0.087	0.099	2.210	2.515
*Y	0.062	0.074	1.575	1.880

* EXPOSED PAD

- NOTES:
1. D&E DO NOT INCLUDE MOLD FLASH.
 2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED 0.15mm (.006").
 3. CONTROLLING DIMENSION: MILLIMETERS.
 4. EXPOSED PAD FLUSH WITH BOTTOM OF PACKAGE WITHIN .002".
 5. MEETS JEDEC MO187.
 6. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
 7. COPLANARITY SHALL NOT EXCEED 0.10mm.

-DRAWING NOT TO SCALE-

DALLAS SEMICONDUCTOR **MAXIM**

TITLE:
PACKAGE OUTLINE, 10L uMAX/uSOP, EXPOSED PAD

APPROVAL	DOCUMENT CONTROL NO. 21-0109	REV. D	1/1
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